

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ013NE2LS5I	**Issued**	02. June 2021
MA#	MA001384692		
Package	PG-TSDSON-8-26	**Weight***	35.88 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.692	1.93	1.93	19288	19288
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		101	
	non noble metal	zinc	7440-66-6	0.015	0.04		405	
	non noble metal	iron	7439-89-6	0.291	0.81		8103	
	non noble metal	copper	7440-50-8	11.804	32.90	33.76	329011	337620
wire	non noble metal	copper	7440-50-8	0.013	0.04	0.04	354	354
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		973	
	plastics	epoxy resin	-	1.798	5.01		50125	
	inorganic material	silicondioxide	60676-86-0	15.627	43.56	48.67	435550	486648
leadfinish	non noble metal	tin	7440-31-5	0.395	1.10	1.10	11017	11017
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	566	566
solder	non noble metal	tin	7440-31-5	0.019	0.05		538	
	noble metal	silver	7440-22-4	0.024	0.07		672	
	non noble metal	lead	7439-92-1	0.921	2.57	2.69	25676	26886
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		141	
	non noble metal	iron	7439-89-6	0.101	0.28		2823	
	non noble metal	copper	7440-50-8	4.112	11.46	11.75	114622	117621
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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